

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended): A semiconductor wafer obtained, at least, by removing a mechanical damage layer by etching both of opposite front and back surfaces of the wafer, flattening the back surface by a surface-grinding means to the exclusion of the front surface of the wafer, polishing both of the front and back surfaces, and then subjecting the front surface of the wafer to a finishing mirror-polishing when defining the surface subjected to surface-grinding as the back surface of the wafer, whereby the front surface of the wafer has no grinding striations but the back surface of the wafer has grinding striations.

2-5. (Cancelled).

6. (Currently Amended): A semiconductor wafer, wherein the wafer has opposite front and back surfaces, the front surface is subjected to a finishing mirror-polishing without being subjected to surface-grinding, the back surface is subjected to surface-grinding, and micro roughness formed during surface-grinding remains on the back surface, whereby the front surface of the wafer has no grinding striations but the back surface of the wafer has grinding striations.

7. (Previously Presented): The semiconductor wafer according to claim 6, wherein the micro roughness on the back surface has P-V value of 30-50 nm and intervals of 1-10 mm.